

Product Change Notification - RMES-10TYKT692

Date:

18 Jul 2019

Product Category:

Motor Drivers

Affected CPNs:



Notification subject:

CCB 3674 Final Notice: Qualification of NSEB as a new assembly site for selected products available in 8L DFN (4x4x0.9mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for selected products available in 8L DFN (4x4x0.9mm) package.

Pre Change:

Assembled at LPI using gold (Au) bond wire, 8340 die attach, G770HT molding compound and C194 lead frame material.

Post Change:

Assembled at NSEB using gold (Au) bond wire, 8600 die attach, G700LTD molding compound and C194 lead frame material.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	UTAC Thai Limited (UTL-1) LTD. (NSEB)				
Wire material	Au	Au				
Die attach material	8340	8600				
Molding compound material	G770HT	G700LTD				
Lead frame material	C194	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualifying NSEB as a new assembly site.



Change Implementation Status:

In Progress

Estimated First Ship Date:

August 15, 2019 (date code: 1933)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	January 2019				,	July 2019				August 2019					
Workweek	01	02	03	04	05	>	27	28	29	30	31	32	33	34	35
Initial PCN Issue Date			X												
Qual Report															
Availability									^						
Final PCN Issue Date									Χ						
Estimated													>		
Implementation Date													^		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN # Qual Report.

Revision History:

January 16, 2019: Issued initial notification.

July 17, 2019: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 15, 2019. Updated time table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN RMES-10TYKT692 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MCP8063-E/MD MCP8063-E/MDVAO MCP8063T-E/MD

Date: Thursday, July 18, 2019